

# 74LVC125A

Quad buffer/line driver with 5 V tolerant input/outputs; 3-state

Rev. 5 — 8 February 2012

Product data sheet

## 1. General description

The 74LVC125A consists of four non-inverting buffers/line drivers with 3-state outputs ( $nY$ ) that are controlled by the output enable input ( $nOE$ ). A HIGH at  $nOE$  causes the outputs to assume a high-impedance OFF-state.

Inputs can be driven from either 3.3 V or 5 V devices. When disabled, up to 5.5 V can be applied to the outputs.

## 2. Features and benefits

- 5 V tolerant inputs/outputs for interfacing with 5 V logic
- Wide supply voltage range from 2.3 V to 3.6 V
- CMOS low power consumption
- Direct interface with TTL levels
- Complies with JEDEC standard JESD8-B/JESD36
- Complies with JEDEC standard:
  - ◆ JESD8-7A (1.65 V to 1.95 V)
  - ◆ JESD8-5A (2.3 V to 2.7 V)
  - ◆ JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-B exceeds 200 V
  - ◆ CDM JESD22-C101E exceeds 1000 V
- Specified from  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$  and  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$

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胜特力电子(上海) 86-21-34970699  
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### 3. Ordering information

**Table 1. Ordering information**

Type number	Package	Temperature range	Name	Description	Version
74LVC125AD	SO14	-40 °C to +125 °C		plastic small outline package; 14 leads; body width 3.9 mm; body thickness 1.47 mm	SOT108-1
74LVC125ADB	SSOP14	-40 °C to +125 °C		plastic shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1
74LVC125APW	TSSOP14	-40 °C to +125 °C		plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74LVC125ABQ	DHVQFN14	-40 °C to +125 °C		plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	SOT762-1

### 4. Functional diagram

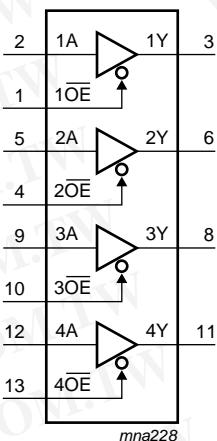


Fig 1. Logic symbol

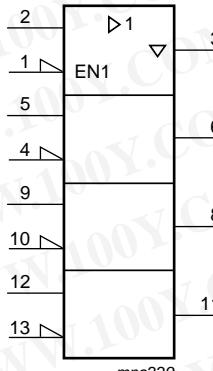


Fig 2. IEC logic symbol

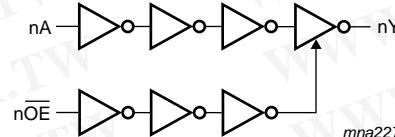


Fig 3. Logic diagram

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## 5. Pinning information

### 5.1 Pinning

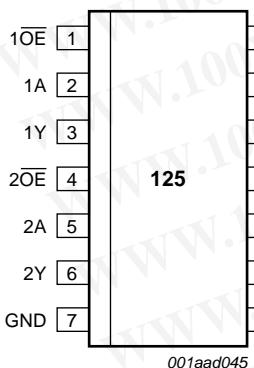


Fig 4. Pin configuration for SO14 and (T)SSOP14

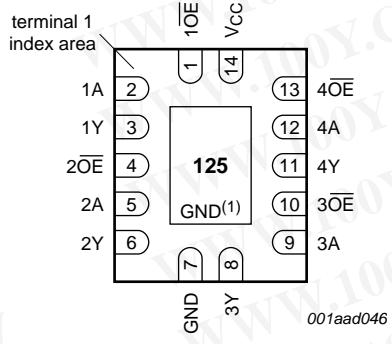


Fig 5. Pin configuration for DHVQFN14

- (1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1OE, 2OE, 3OE, 4OE	1, 4, 10, 13	data enable input (active LOW)
1A, 2A, 3A, 4A	2, 5, 9, 12	data input
1Y, 2Y, 3Y, 4Y	3, 6, 8, 11	data output
GND	7	ground (0 V)
V <sub>CC</sub>	14	supply voltage

## 6. Functional description

Table 3. Function selection<sup>[1]</sup>

Inputs		Output
nOE	nA	nY
L	L	L
L	H	H
H	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state

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## 7. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+6.5	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < 0 V	-50	-	mA
V <sub>I</sub>	input voltage		[1]	-0.5	+6.5
I <sub>OK</sub>	output clamping current	V <sub>O</sub> > V <sub>CC</sub> or V <sub>O</sub> < 0 V	-	±50	mA
V <sub>O</sub>	output voltage	output HIGH or LOW-state	[2]	-0.5	V <sub>CC</sub> + 0.5 V
		output 3-state	[2]	-0.5	+6.5 V
I <sub>O</sub>	output current	V <sub>O</sub> = 0 V to V <sub>CC</sub>	-	±50	mA
I <sub>CC</sub>	supply current		-	100	mA
I <sub>GND</sub>	ground current		-100	-	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C	[3]	-	500 mW
T <sub>stg</sub>	storage temperature		-65	+150	°C

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] For SO14 packages: above 70 °C derate linearly with 8 mW/K.

For (T)SSOP14 packages: above 60 °C derate linearly with 5.5 mW/K.

For DHVQFN14 packages: above 60 °C derate linearly with 4.5 mW/K.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>CC</sub>	supply voltage		1.65	-	3.6	V
		functional	1.2	-	-	V
V <sub>I</sub>	input voltage		0	-	5.5	V
V <sub>O</sub>	output voltage	output HIGH or LOW state	0	-	V <sub>CC</sub>	V
		output 3-state	0	-	5.5	V
T <sub>amb</sub>	ambient temperature		-40	-	+125	°C
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 2.3 V to 2.7 V	0	-	20	ns/V
		V <sub>CC</sub> = 2.7 V to 3.6 V	0	-	10	ns/V

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## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 1.2 V	1.08	-	-	1.08	-	V
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>	-	-	0.65 × V <sub>CC</sub>	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7	-	-	1.7	-	V
		V <sub>CC</sub> = 2.7 V to 3.6 V	2.0	-	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 1.2 V	-	-	0.12	-	0.12	V
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	-	0.35 × V <sub>CC</sub>	-	0.35 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	-	0.7	V
		V <sub>CC</sub> = 2.7 V to 3.6 V	-	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>						
		I <sub>O</sub> = -100 μA; V <sub>CC</sub> = 1.65 V to 3.6 V	V <sub>CC</sub> - 0.2	-	-	V <sub>CC</sub> - 0.3	-	V
		I <sub>O</sub> = -4 mA; V <sub>CC</sub> = 1.65 V	1.2	-	-	1.05	-	V
		I <sub>O</sub> = -8 mA; V <sub>CC</sub> = 2.3 V	1.8	-	-	1.65	-	V
		I <sub>O</sub> = -12 mA; V <sub>CC</sub> = 2.7 V	2.2	-	-	2.05	-	V
		I <sub>O</sub> = -18 mA; V <sub>CC</sub> = 3.0 V	2.4	-	-	2.25	-	V
		I <sub>O</sub> = -24 mA; V <sub>CC</sub> = 3.0 V	2.2	-	-	2.0	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>						
		I <sub>O</sub> = 100 μA; V <sub>CC</sub> = 1.65 V to 3.6 V	-	-	0.2	-	0.3	V
		I <sub>O</sub> = 4 mA; V <sub>CC</sub> = 1.65 V	-	-	0.45	-	0.65	V
		I <sub>O</sub> = 8 mA; V <sub>CC</sub> = 2.3 V	-	-	0.6	-	0.8	V
		I <sub>O</sub> = 12 mA; V <sub>CC</sub> = 2.7 V	-	-	0.4	-	0.6	V
		I <sub>O</sub> = 24 mA; V <sub>CC</sub> = 3.0 V	-	-	0.55	-	0.8	V
I <sub>I</sub>	input leakage current	V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = 5.5 V or GND	-	±0.1	±5	-	±20	μA
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 3.6 V; V <sub>O</sub> = 5.5 V or GND	-	±0.1	±5	-	±20	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>CC</sub> = 0.0 V; V <sub>I</sub> or V <sub>O</sub> = 5.5 V	-	±0.1	±10	-	±20	μA
I <sub>CC</sub>	supply current	V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A	-	0.1	10	-	40	μA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 2.7 V to 3.6 V	-	5	500	-	5000	μA
C <sub>I</sub>	input capacitance	V <sub>CC</sub> = 0 V to 3.6 V; V <sub>I</sub> = GND to V <sub>CC</sub>	-	4.0	-	-	-	pF

[1] All typical values are measured at V<sub>CC</sub> = 3.3 V (unless stated otherwise) and T<sub>amb</sub> = 25 °C.

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## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$t_{pd}$	propagation delay	nA to nY; see <a href="#">Figure 6</a>	[2]					
		$V_{CC} = 1.2 \text{ V}$	-	12.0	-	-	-	ns
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	1.5	5.4	11.0	1.5	12.8	ns
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.0	2.9	5.7	1.0	6.7	ns
		$V_{CC} = 2.7 \text{ V}$	1.5	2.8	5.5	1.5	7.0	ns
$t_{en}$	enable time	$\overline{nOE}$ to nY; see <a href="#">Figure 7</a>	[2]					
		$V_{CC} = 1.2 \text{ V}$	-	16.0	-	-	-	ns
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	1.0	5.0	12.2	1.0	14.2	ns
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	0.5	2.9	6.8	0.5	7.9	ns
		$V_{CC} = 2.7 \text{ V}$	1.5	3.1	6.6	1.5	8.5	ns
$t_{dis}$	disable time	$\overline{nOE}$ to nY; see <a href="#">Figure 7</a>	[2]					
		$V_{CC} = 1.2 \text{ V}$	-	7.0	-	-	-	ns
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	2.2	4.6	7.5	2.2	8.7	ns
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	0.5	2.6	4.2	0.5	5.0	ns
		$V_{CC} = 2.7 \text{ V}$	1.5	3.1	5.0	1.5	6.5	ns
$t_{sk(o)}$	output skew time	$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	[3]					
		per buffer; $V_I = \text{GND to } V_{CC}$	[4]					
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	-	6.0	-	-	-	pF
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	-	9.4	-	-	-	pF
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	-	12.4	-	-	-	pF
$C_{PD}$	power dissipation capacitance							

[1] Typical values are measured at  $T_{amb} = 25 \text{ }^{\circ}\text{C}$  and  $V_{CC} = 1.2 \text{ V}, 1.8 \text{ V}, 2.5 \text{ V}, 2.7 \text{ V}$ , and  $3.3 \text{ V}$  respectively.

[2]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .

$t_{en}$  is the same as  $t_{PZL}$  and  $t_{PZH}$ .

$t_{dis}$  is the same as  $t_{PLZ}$  and  $t_{PHZ}$ .

[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[4]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where:

$f_i$  = input frequency in MHz;  $f_o$  = output frequency in MHz

$C_L$  = output load capacitance in pF

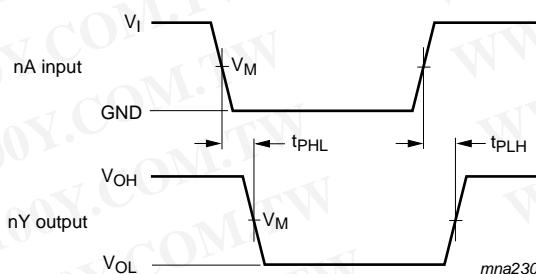
$V_{CC}$  = supply voltage in Volts

N = number of inputs switching

$\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.

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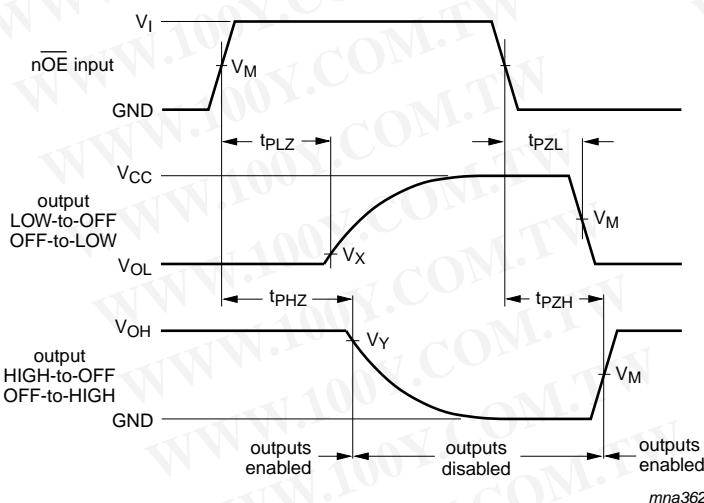
## 11. AC waveforms



Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

Fig 6. The input nA to output nY propagation delays



Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

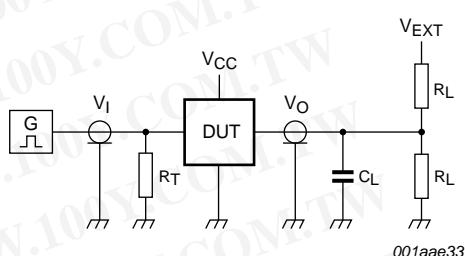
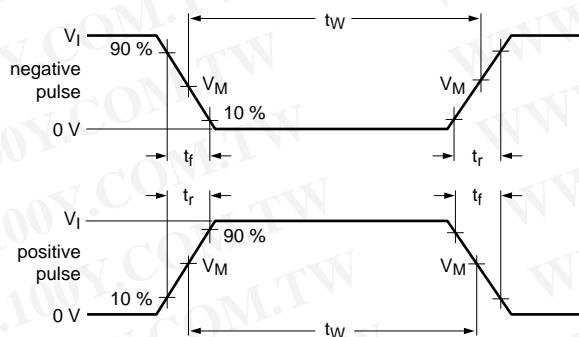
Fig 7. 3-state enable and disable times

Table 8. Measurement points

Supply voltage	Input	Output
$V_{CC}$	$V_M$	$V_M$
$V_{CC} < 2.7 \text{ V}$	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
$V_{CC} \geq 2.7 \text{ V}$	$1.5 \text{ V}$	$1.5 \text{ V}$
		$V_X$
		$V_Y$
		$V_{OL} + 0.15 \text{ V}$
		$V_{OH} - 0.15 \text{ V}$
		$V_{OL} + 0.3 \text{ V}$
		$V_{OH} - 0.3 \text{ V}$

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Test data is given in [Table 9](#).

Definitions for test circuit:

$R_L$  = Load resistance.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$V_{EXT}$  = External voltage for measuring switching times.

**Fig 8. Test circuit for measuring switching times**

**Table 9. Test data**

Supply voltage	Input		Load		$V_{EXT}$		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PLH}, t_{PHL}$	$t_{PLZ}, t_{PZL}$	$t_{PHZ}, t_{PZH}$
1.2 V	$V_{CC}$	$\leq 2$ ns	30 pF	1 k $\Omega$	open	$2 \times V_{CC}$	GND
1.65 V to 1.95 V	$V_{CC}$	$\leq 2$ ns	30 pF	1 k $\Omega$	open	$2 \times V_{CC}$	GND
2.3 V to 2.7 V	$V_{CC}$	$\leq 2$ ns	30 pF	500 $\Omega$	open	$2 \times V_{CC}$	GND
2.7 V	2.7 V	$\leq 2.5$ ns	50 pF	500 $\Omega$	open	$2 \times V_{CC}$	GND
3.0 V to 3.6 V	2.7 V	$\leq 2.5$ ns	50 pF	500 $\Omega$	open	$2 \times V_{CC}$	GND

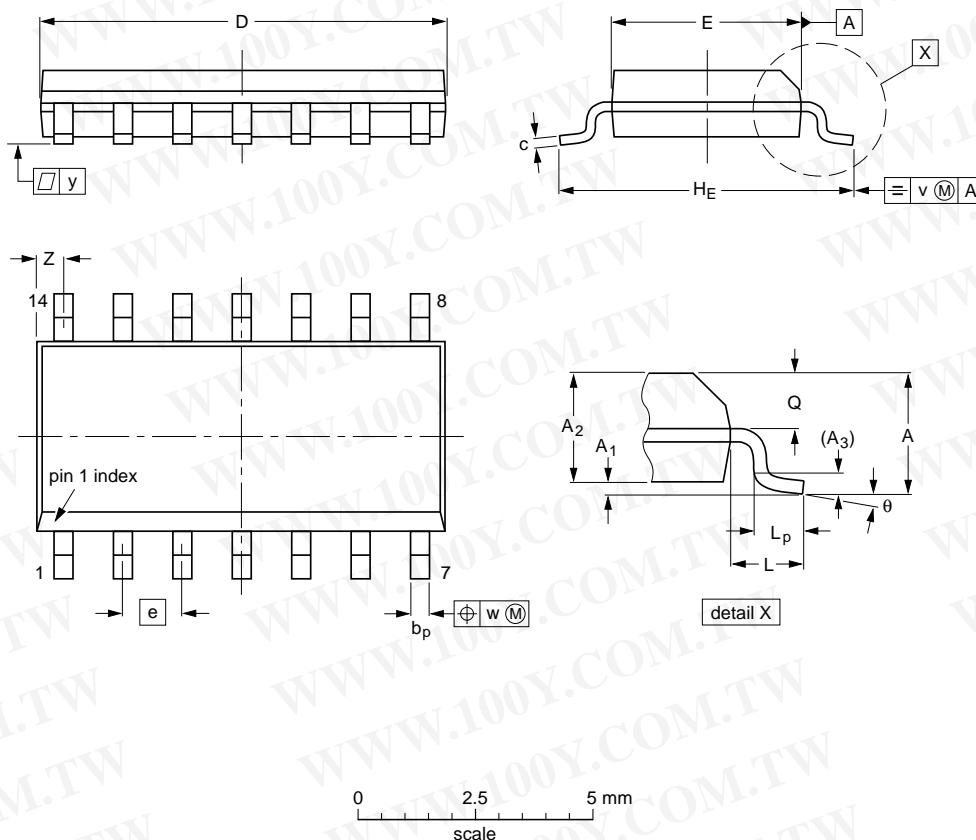
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## 12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.75 0.10	0.25 1.25	1.45	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069 0.004	0.010 0.049	0.057	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT108-1	076E06	MS-012				99-12-27 03-02-19

Fig 9. Package outline SOT108-1 (SO14)

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Quad buffer/line driver with 5 V tolerant input/outputs; 3-state

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

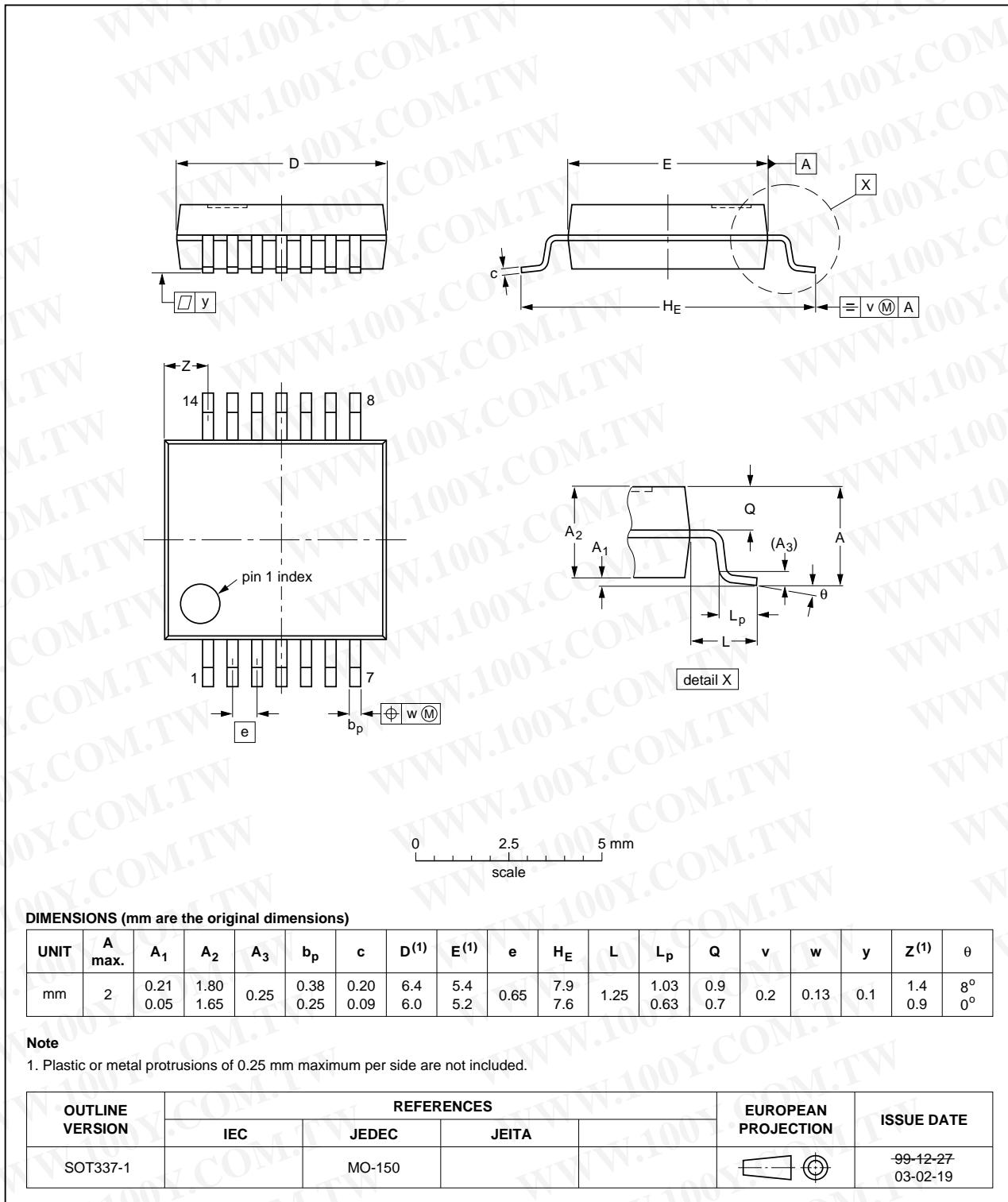


Fig 10. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

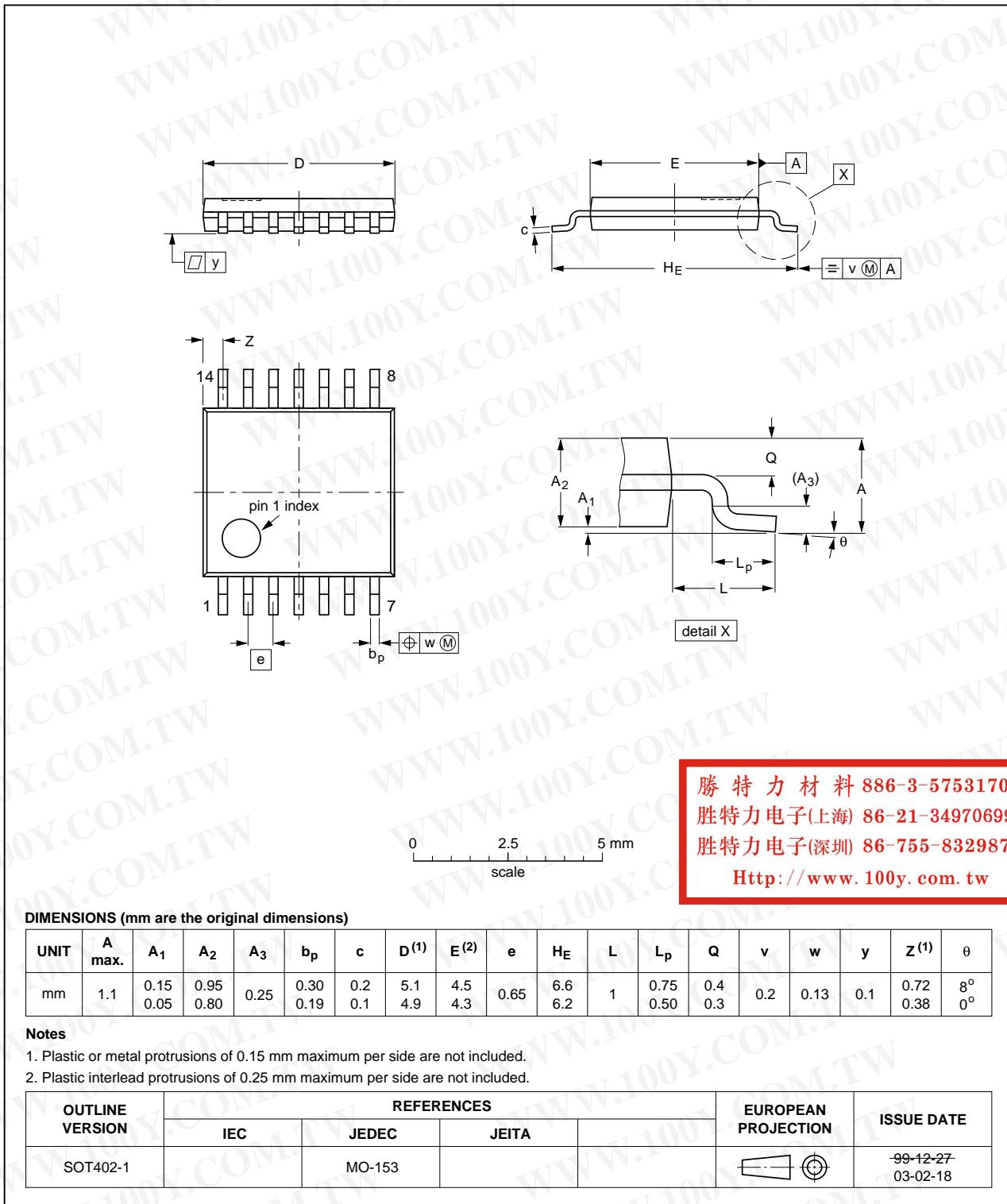


Fig 11. Package outline SOT402-1 (TSSOP14)

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Quad buffer/line driver with 5 V tolerant input/outputs; 3-state

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;  
 14 terminals; body 2.5 x 3 x 0.85 mm SOT762-1

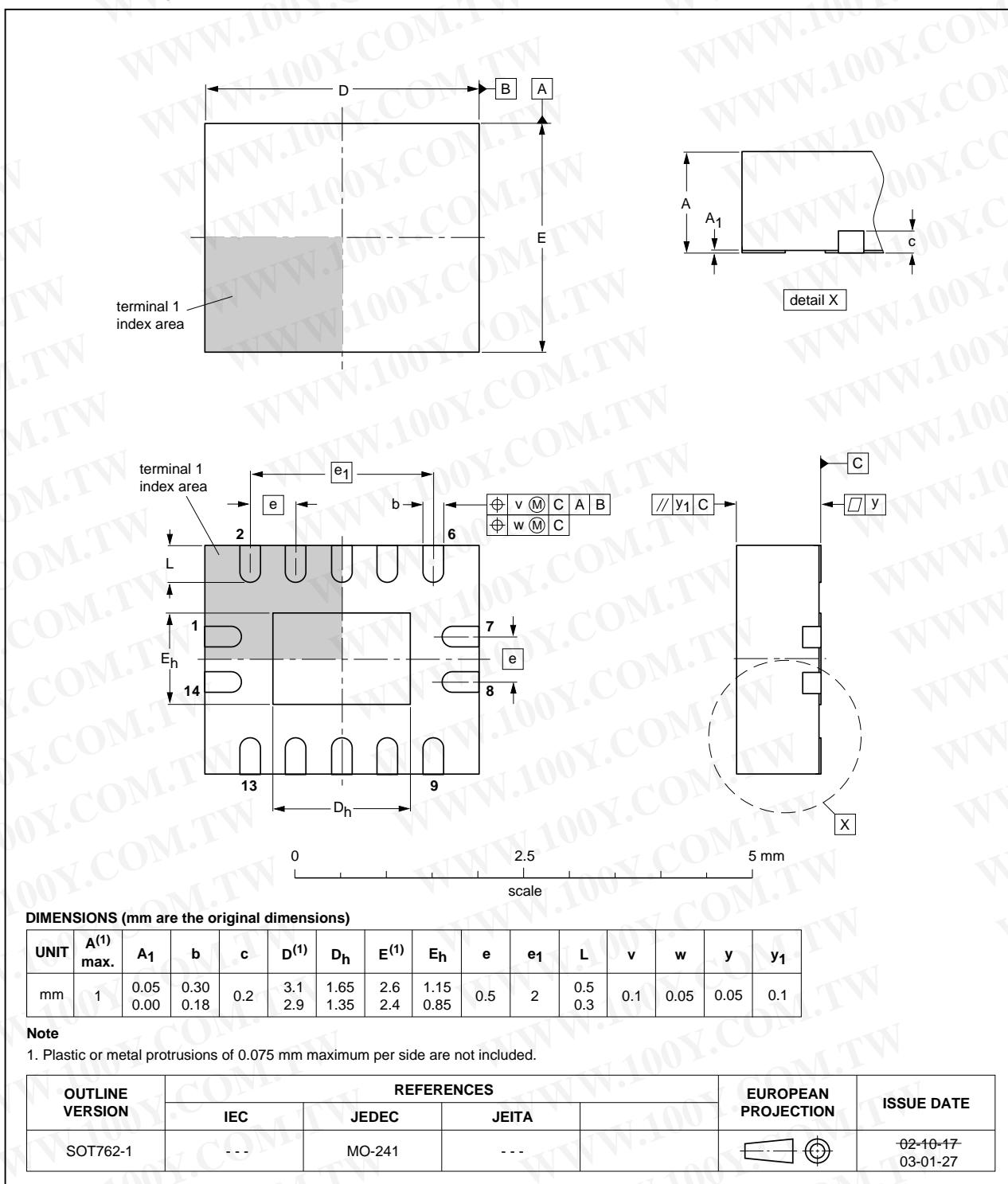


Fig 12. Package outline SOT762-1 (DHVQFN14)

## 13. Abbreviations

**Table 10. Abbreviations**

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
MM	Machine Model
HBM	Human Body Model
TTL	Transistor-Transistor Logic

## 14. Revision history

**Table 11. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC125A v.5	20120208	Product data sheet	-	74LVC125A v.4
Modifications:	<ul style="list-style-type: none"> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li><a href="#">Table 4</a>, <a href="#">Table 5</a>, <a href="#">Table 6</a>, <a href="#">Table 7</a>, and <a href="#">Table 9</a>: values added for lower voltage ranges.</li> </ul>			
74LVC125A v.4	20030507	Product specification	-	74LVC125A v.3
74LVC125A v.3	20020308	Product specification	-	74LVC125A v.2
74LVC125A v.2	19980428	Product specification	-	74LVC125A v.1
74LVC125A v.1	19970801	Product specification	-	-

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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